L Number	Hits	Search Text	DB	Time stamp
1	3005	wafer same level same (package packaging packaged)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/22 15:54
2	96	(trench groove) same (wafer same level same (package packaging packaged))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/22

L	Hits	Search Text	DB	Time stamp
Number				
1	10877	wafer same trench	USPAT;	2004/02/22
			US-PGPUB;	15:23
-			EPO; JPO;	
			DERWENT;	i
			IBM_TDB	
2	210	'	USPAT;	2004/02/22
Ì		packages packaged)	US-PGPUB;	15:24
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
3	51047	chip with size	USPAT;	2004/02/22
			US-PGPUB;	15:24
			EPO; JPO;	
			DERWENT;	
	ļ		IBM_TDB	
4	69	( (	USPAT;	2004/02/22
		packages packaged)) and (chip with size)	US-PGPUB;	15:24
	'		EPO; JPO;	
			DERWENT;	]
			IBM_TDB	